




Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EPLM*P0211M1	A	Z4XA	2016-02-16
Amount	UoM	Unit type	ST ECOPACK Grade	
110.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOT	3.5- 6.5 - 1.8	4	gull wing	
Comment	Package: SOT 223 PLANAR and TOPGLASS, MD valid for CP:P0111MN 5AA4.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices

QueryList : REACH-17th December 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EPLM*P0211M1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	0.718	mg	supplier	die	Silicon (Si)	7440-21-3		0.63	mg	877437	5727
Silicon die				supplier	metallization	Aluminium (Al)	7429-90-5		0.01	mg	13928	91
Silicon die				supplier	passivation	Alumina	1344-28-1		0.007	mg	9749	64
Silicon die				JIG - R	passivation	Lead silicate Glass	65997-18-4	7c-I-Electrical and e	0.061	mg	84958	555
Silicon die				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.004	mg	5571	36
Silicon die				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1393	9
Silicon die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.005	mg	6964	45
Leadframe	Copper & its alloys	58.8	mg	supplier	alloy	Copper(Cu)	7440-50-8		58.01	mg	986565	527364
Leadframe				supplier	alloy	Iron(Fe)	7439-89-6		0.058	mg	986	527
Leadframe				supplier	alloy	Phosphorus(P)	12185-10-3		0.017	mg	289	155
Leadframe				supplier	metallization	Silver(Ag)	7440-22-4		0.715	mg	12160	6500
Soft solder	Solder	1.504	mg	JIG - R	solder	Lead(Pb)	7439-92-1	7a-Lead in high me	1.436	mg	954787	13055
Soft solder				supplier	solder	Silver(Ag)	7440-22-4		0.038	mg	25266	345
Soft solder				supplier	solder	Tin(Sn)	7440-31-5		0.03	mg	19947	273
Bonding wire	Other Inorganic Material	0.156	mg	Supplier	wire	Copper(Cu)	7440-50-8		0.156	mg	1000000	1418
encapsulation	Other Inorganic Material	47.777	mg	supplier	mold compound	Silica Fused	60676-86-0		42.043	mg	879984	382209
encapsulation				supplier	mold compound	Epoxy,Cresol Novolac	29690-82-2		0.717	mg	15007	6518
encapsulation				supplier	mold compound	Phenol Resin	26834-02-6		2.389	mg	50003	21718
encapsulation				supplier	mold compound	Epoxy Resin	Proprietary		2.389	mg	50003	21718
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.239	mg	5002	2173
connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	9500